

**Thermal resistance**

Parameter□	Symbol□	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	0.8	° C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	31	° C/W
Soldering temperature, wave soldering for 10s	T_{sold}	-	-	265	° C

Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.3	1.9	2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			100	nA
Static Drain-source On Resistance		$V_{GS}=10V, I_D=25A$				
		$V_{GS}=4.5V, I_D=15A$				
Forward Transconductance	g_{FS}	$V_{DS}=25V, I_D=10A$				
Source-drain voltage	V_{SD}	$I_S=25A$				

Electronic Characteristics

Parameter	Symbol
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Fig.1 Gate



Fig.13 Avalanche Measurement Circuit

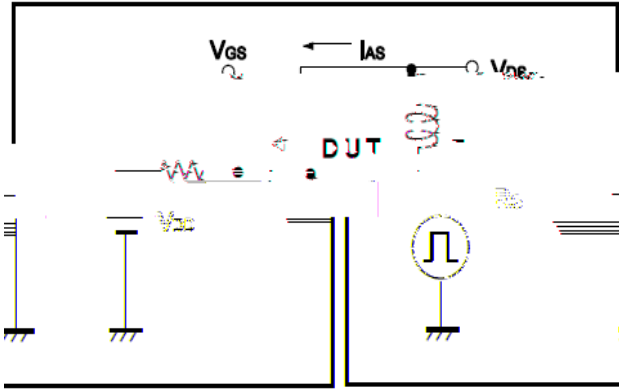
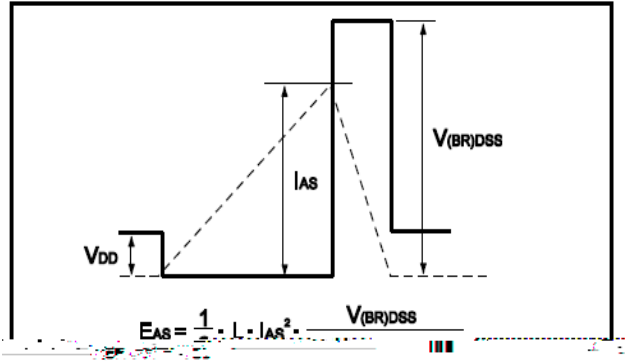


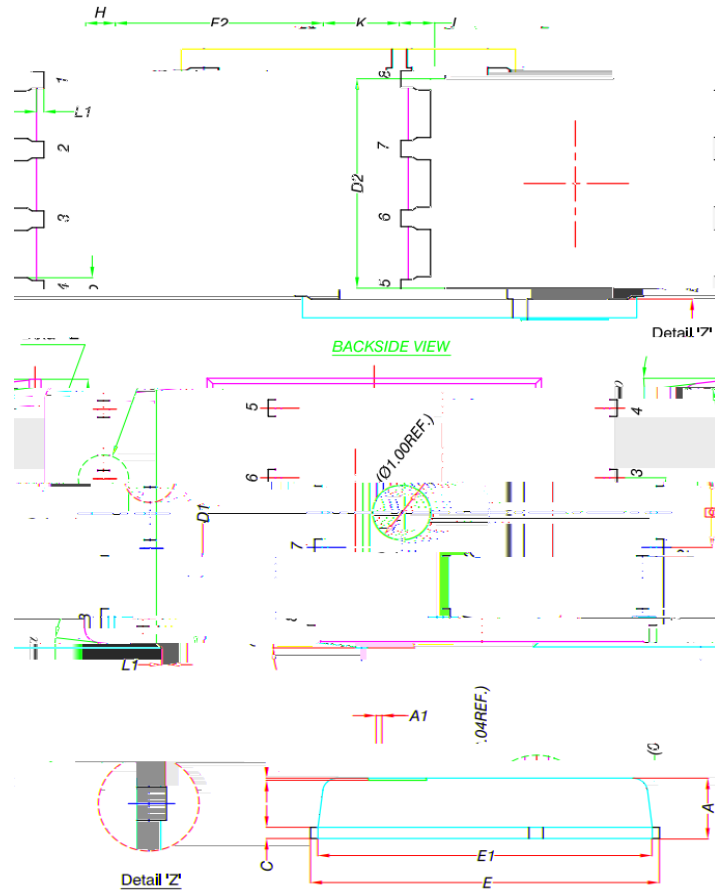
Fig.14 Avalanche Waveform





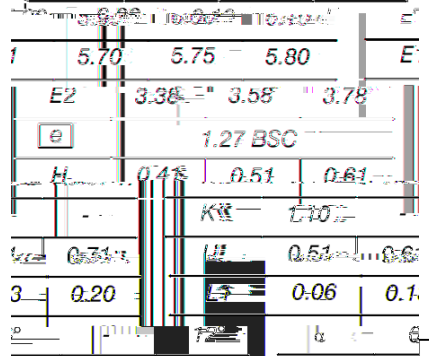
Dimensions DFN5x6

Unit mm



□

DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96



□